



Product Change Notification - RMES-31VQKE033

Date:

22 May 2019

Product Category:

Depletion Mode MOSFETs; Linear Regulator ICs

Affected CPNs:**Notification subject:**

CCB 3458 Initial Notice: Qualification of GTBF as a new assembly site for selected products available in 3L TO-220 package using 277 x 221 mils paddle size.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTBF as a new assembly site for selected products available in 3L TO-220 package using 277 x 221 mils paddle size.

Pre Change:

Assembled at CARSEM using 2815A die attach, HCL-12S lead frame with 240 x 180 mils paddle size and CEL9240HF-10CM molding compound material

Post Change:

Assembled at GTBF using CRM-1800 die attach, LY80 lead frame with 277 x 221 mils paddle size and EME-G600 molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Carsem (M) SDN BHD (CARM)	Great Team Backend Foundry (Dong Guan) Ltd. (GTBF)
Wire material	Au wire	Au wire
Die attach material	2815A	CRM-1800
Molding compound material	CEL9240HF-10CM	EME-G600
Lead frame material	HCL-12S	LY80
Lead frame paddle size	240 x 180 mils	277 x 221 mils

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTBF as a new assembly site using 277 x 221 mils paddle size. CARM assembly site will no longer have manufacturing support for 3L TO-220 package.



Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					>	June 2019				
Workweek	31	32	33	34	35		22	23	24	25	26
Initial PCN Issue Date		X									
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

August 09, 2018: Issued initial notification.

May 22, 2019: Re-issued initial notification. Added Lead frame paddle size information in notification subject, description of change and Pre and Post change summary table. Updated qualification plan to change the qual vehicle.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-31VQKE033_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

CL6N5-G

DN2535N5-G

DN2540N5-G